L Numb r	Hits	Search Text	DB	Time stamp
1	0	conduct\$3 adj assemb\$3 near solderless	USPAT; US-P PUB; EP ; JP ;	2004/02/26 08:29
2	62	conduct\$3 near solderless	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2004/02/26 08:30
3	29	conduct\$3 near assembly and spring near force and hook	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2004/02/26 08:32
4	291	conduct\$3 near assembly and spring near force	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2004/02/26 08:33
55	923	439/79.ccls.	DERWENT; IBM_TDB USPAT; US-PGPUB;	2004/02/26 08:33
6	21	439/79.ccis. and solderless	EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2004/02/26 08:36
7 .	3	contact near assembly and solderless and (439/79; 439/108 ; 439/101 ; 439/701 ; 439/247).ccls.	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2004/02/26 08:49
8	14	("3444502" "3744009" "3794953" "3842189" "3883207" "3885848" "4113342" "4186988" "4262981" "4286835" "4296991" "4386815"	DERWENT; IBM_TDB USPAT	2004/02/26 08:37
9	6	"4422128" "4457570").PN. ("2905921" "3771101" "3865454" "3868166" "3871728" "4089581").PN.	USPAT	2004/02/26 08:39
11	10	4089581.URPN. ("3137537" "3848221" "3899234" "4068170" "4089581" "4279459"	USPAT	2004/02/26 08:40 2004/02/26 08:41

12	3	c ntact near assembly and solderless and (439/265, 29/832, 439/260, 439/266, 439/267, 439/325 339/74R; 339/75M; 339/75MP; 339/176MP; 29/832; 29/834; 29/842;439/79; 439/108; 439/101; 439/701; 439/247).ccls.	USPAT; US-P PUB; EP ; JP ; DERWENT; IBM_TDB	2004/02/26 08:50
13	8	creighton near david .inv.	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/02/26 08:51
14	2	creighton near david .inv. and assembly	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/02/26 09:33
15	1946	29/739.ccls.	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/02/26 09:34
16	7	29/739.ccls. and contact near assembly	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/26 09:34
17	15	29/832-836.ccis. and contact near assembly	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/02/26 09:36
18	43	contact near assembly and (29/832, 257/E23.065 , 257/E23.066 , 257/E23.07 , 257/E23.124 , 29/827 , 29/840 , 29/844).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/26 09:38
19	180	contact near assembly and (439/140; 439/374; 439/79; 439/248; 439/271; 439/609; 29/874; 29/882; 29/840; 361/403; 361/409; 361/410; 264/272.14; 264/272.17).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/26 09:38
20	3	contact near assembly and solderless and (439/140; 439/374; 439/79; 439/248; 439/271; 439/609; 29/874; 29/882; 29/840; 361/403; 361/409; 361/410; 264/272.14; 264/272.17).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/26 09:38

21	7	spring adj contact near assembly and (439/140; 439/374; 439/79; 439/248; 439/271; 439/609; 29/874; 29/882; 29/840; 361/403; 361/409; 361/410; 264/272.14; 264/272.17).ccls.	USPAT; US-P PUB; EP ; JP ; DERWENT; IBM_TDB	2004/02/26 09:39

		439/347;
C nn ctor for mating modular plug with	720/50	439/507;
		439/629;
		439/676
		174/261;
		174/267;
•••••		361/772;
Push- n t rminal clip and assembly	361/776	439/81;
		439/816;
		439/83
		29/830;
	439/81	439/259:
m dul na circuit board or the like		439/65
		379/442:
El ctrical connector receptacle 4	439/676	439/82
		439/493;
Modular t lephone connector	439/395	439/76.1
Printed circuit board connector	439/62	439/634
otacles	439/676	439/75
		439/68;
C nduct r arrangement and assembly	439/630	968/881;
m th d		968/DIG.1
El ctrical connection and method of	439/841	
making ame		
ion force connector for modular	439/264	439/746

	Titi	Curr nt OR	Curr nt XR f
7-	CONTACT ARRAY AND METHOD OF MAKING THE SAME	174/52.3	136/213; 174/52.4; 257/712; 257/723; 257/785; 257/786; 361/776; 439/66
12	ELECTRICAL TERMINAL FOR CONDUCTIVE FOIL	439/329	174/117A; 174/267; 439/371; 439/571; 439/801; 439/917
13	PCB SURFACE CONNECTOR	439/329	439/345 ; 439/557
14	MEANS FOR MAKING AN ELECTRICAL CONNECTION BETWEEN AN ELECTRICAL COMPONENT AND A PRINTED CIRCUIT	439/81	439/329; 439/621

		Tit	Curr nt OR	Curr nt XR f
	Electri	mponent insertion apparatus	29/33M	29/739; 29/741
	Aut matic test system	sst system	324/754	29/739
	D vic f r in ard	r inserting contacts on a support	29/739	29/235; 29/747; 29/844; 29/881
_	S If-masking s circuit boards	lf-masking socket pin carrier for printed rcuit boards	29/739	228/180.1; 228/49.5; 228/58; 29/843; 414/736; 439/83; 439/83;
	M thod for a connector	M thod for assembly of electrical connector	29/884	29/739
46	M th dfrr electrical int	M th df r mounting lead sockets to an electrical interconnection board	29/844	29/525; 29/739; 29/743
	METHOD AND APPARATU ASSEMBLY OF CONTACT CIRCUIT BOARD	PPARATUS FOR ONTACTS IN A PRINTED	29/843	29/739

<u>-3</u> .				
L Number	Hits	Search Text	DB	Time stamp
1	2	6625881.pn.	USPAT;	2004/02/26
-	_		US-PGPUB:	
			EP ; JP ;	10.47
			DERWENT;	
			IBM_TDB	
2	20	("4867696" "4890199" "5053926"	USPAT	2004/02/26
-		"5129832" "5188534" "5239127"	USFAI	10:33
		"5366380" "5373101" "5595490"		10:33
		"5617866" "5639263" "5641314"		
		"5748455" "5820549" "5896107"		
		"5967800" "5991165" "6025806"		
		"6142802" "6200171").PN.		
3	38	("3550062" "3815077" "3873173"	HEDAT	2004/00/00
3	30	, .	USPAT	2004/02/26
		"3960424" "3993384" "4035046"		10:36
		"4050755" "4052118" "4057311"		
		"4093330" "4176895" "4188085"		
		"4220383" "4268102" "4341433"		
		"4359252" "4494807" "4511201"		
		"4553192" "4660920" "4664458"		
·		"4806104" "4927369" "4995814"		
		"4998886" "5041016" "5052943"		
		"5199889" "5226826" "5230632"		
		"5234353" "5259769" "5306163"		
		"5308252" "5310352" "5378160"		
		"5584713" "5586890").PN.		
4	20	("4867696" "4890199" "5053926"	USPAT	2004/02/26
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		"5366380" "5373101" "5595490"		
		"5617866" "5639263" "5641314"		
		"5748455" "5820549" "5896107"		
		"5967800" "5991165" "6025806"		
		"6142802" "6200171").PN.		
5	38	("3550062" "3815077" "3873173"	USPAT	2004/02/26
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:		"4050755" "4052118" "4057311"		
		"4093330" "4176895" "4188085"		
		"4220383" "4268102" "4341433"		
		"4359252" "4494807" "4511201"		
		"4553192" "4660920" "4664458"		
		"4806104" "4927369" "4995814"		
		"4998886" "5041016" "5052943"		
		"5199889" "5226826" "5230632"		
		"5234353" "5259769" "5306163"		
		"5308252" "5310352" "5378160"		
		"5584713" "5586890").PN.		
6	7	("4527848" "4857001" "4891019"	USPAT	2004/02/26
	•	"5002495" "5055054" "5104326"	30171	10:44
		"5161985").PN.		1 · · · · · · ·
7	5	("3736471" "3905670" "3960424"	HEDAT	2004/02/26
•	J	, .	USPAT	2004/02/26
		"4330163" "4350403").PN.		10:45

, a				
8	3	("3868154" "3960424" "4664458").PN.	USPAT	2004/02/26
				10:47
9	21	Ammar near Danny.inv.	USPAT;	2004/02/26
			US-P PUB;	10:48
			EP ; JP ;	
			DERWENT;	
			IBM_TDB	
10	2	5188534.pn.	USPAT;	2004/02/26
			US-PGPUB;	10:55
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
11	2	5378160.pn.	USPAT;	2004/02/26
		•	US-PGPUB;	10:56
			EPO; JPO;	10.00
			DERWENT;	
			IBM TDB	
12	24	("3715706" "3795037" "4161346"	USPAT	2004/02/26
		"4199209" "4295700" "4505529"	90. A.	10:56
		"4511196" "4738625" "4806104"		10.50
		"4813129" "4927569" "4983126"		
		"4998886" "5061192" "5069627"		
		"5139427" "5147207" "5152695"		
		"5160268" "5173055" "5199889"		
		"5220270" "5228861" "5259777").PN.		
13	20	("3917372" "4236667" "4288140"	USPAT	2004/02/26
		"4575703" "4717817" "4724310"	JOIAI	10:58
		"4734567" "4735578" "4752234"		10.30
		"4770639" "4795897" "4799891"		
		"4814593" "4850888" "4900273"		
		"4932889" "4971568" "4975086"		
		"4976630" "5013255").PN.		
14	4	("3795888" "4084847" "4530557"	USPAT	2004/02/26
		"4900273").PN.	John	11:00
	0	conduct\$3 adj assemb\$3 near solderless	USPAT;	2004/02/26
			US-PGPUB;	10:32
			EPO; JPO;	. 4.52
			DERWENT;	
			IBM_TDB	
_	62	conduct\$3 near solderless	USPAT;	2004/02/26
			US-PGPUB;	08:30
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
•	29	conduct\$3 near assembly and spring near	USPAT;	2004/02/26
		force and hook	US-PGPUB;	2004/02/26
		10.00 dild Hook	1 - 1	08:32
			EPO; JPO;	
			DERWENT;	
L	l		IBM_TDB	

•	291	c uct\$3 near assembly and spring near	USPAT;	2004/02/26
		force	US-PGPUB;	08:33
			EP ; JP ;	
			DERWENT;	
		, .	IBM_TDB	
_	923	439/79.ccls.	USPAT;	2004/02/26
			US-PGPUB;	08:33
			EPO; JPO;	00:33
			DERWENT:	
			1	
_	21	439/79.ccls. and solderless	IBM_TDB	0004/00/00
		4337 3.ccis. and solderless	USPAT;	2004/02/26
			US-PGPUB;	08:36
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	3	contact near assembly and solderless and	USPAT;	2004/02/26
		(439/79; 439/108 ; 439/101 ; 439/701 ;	US-PGPUB;	08:49
		439/247).ccls.	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	14	("3444502" "3744009" "3794953"	USPAT	2004/02/26
		"3842189" "3883207" "3885848"		08:37
		"4113342" "4186988" "4262981"		
		"4286835" "4296991" "4386815"		
		"4422128" "4457570").PN.		
-	6	("2905921" "3771101" "3865454"	USPAT	2004/02/26
		"3868166" "3871728" "4089581").PN.		08:39
-	7	4089581.URPN.	USPAT	2004/02/26
				08:40
	10	("3137537" "3848221" "3899234"	USPAT	2004/02/26
		"4068170" "4089581" "4279459"		08:41
		"4288140" "4357066" "4428635"		V0:41
		"4431252").PN.		
,	3	contact near assembly and solderless and	HCDAT-	2004/00/00
	•	(439/265, 29/832 , 439/260 , 439/266 ,	USPAT;	2004/02/26
		439/267, 439/325 339/74R; 339/75M;	US-PGPUB;	08:50
		· · ·	EPO; JPO;	
		339/75MP; 339/176MP; 29/832; 29/834;	DERWENT;	
		29/842;439/79; 439/108 ; 439/101 ; 439/701 ;	IBM_TDB	
		439/247).ccls.	İ	
	8	creighton near david .inv.	USPAT;	2004/02/26
			US-PGPUB;	08:51
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
	2	creighton near david .inv. and assembly	USPAT;	2004/02/26
ļ	İ		US-PGPUB;	09:33
		·	EPO; JPO;	-
			DERWENT;	
			IBM_TDB	

			l .	
-	1946	25.039.ccls.	USPAT;	2004/02/26
			US-P PUB;	09:34
			EP ; JPO;	
			DERWENT;	
			IBM_TDB	
-	7	29/739.ccls. and c ntact near assembly	USPAT;	2004/02/26
			US-P PUB;	09:34
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	15	29/832-836.ccls. and contact near assembly	USPAT;	2004/02/26
			US-PGPUB;	09:36
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	43	contact near assembly and (29/832,	USPAT;	2004/02/26
		257/E23.065 , 257/E23.066 , 257/E23.07 ,	US-PGPUB;	09:38
		257/E23.124	EPO; JPO;	
		, 29/827 , 29/840 , 29/844).ccls.	DERWENT;	
			IBM_TDB	
			_	
-	180	contact near assembly and (439/140;	USPAT;	2004/02/26
		439/374 ; 439/79 ; 439/248 ; 439/271 ;	US-PGPUB;	09:38
		439/609; 29/874 ; 29/882 ; 29/840 ; 361/403 ;	EPO; JPO;	
		361/409 ; 361/410 ; 264/272.14 ;	DERWENT;	
		264/272.17).ccls.	IBM_TDB	
-	3	contact near assembly and solderless and	USPAT;	2004/02/26
		(439/140; 439/374 ; 439/79 ; 439/248 ;	US-PGPUB;	09:38
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		361/403 ; 361/409 ; 361/410 ; 264/272.14 ;	DERWENT;	
		264/272.17).ccls.	IBM_TDB	
	7	spring adj contact near assembly and	USPAT;	2004/02/26
		(439/140; 439/374 ; 439/79 ; 439/248 ;	US-PGPUB;	09:39
		439/271 ; 439/609; 29/874 ; 29/882 ; 29/840 ;	EPO; JPO;	
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		264/272.17).ccis.	IBM_TDB	
			18M_188	
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	<u> </u>		<u> </u>	